



Material Content Data Sheet



Sales Product Name		SAF-XC888CLM-8FFI 5V AC		Issued		25. September 2017		
MA#		MA001127800						
Package		PG-LQFP-64-14		Weight*		373.58 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	11.934	3.19	3.19	31946	31946
leadframe	non noble metal	magnesium	7439-95-4	0.172	0.05		459	
	inorganic material	silicon	7440-21-3	0.743	0.20		1990	
	non noble metal	nickel	7440-02-0	3.431	0.92		9184	
	non noble metal	copper	7440-50-8	110.016	29.45	30.62	294490	306123
wire	noble metal	gold	7440-57-5	1.205	0.32	0.32	3224	3224
encapsulation	organic material	carbon black	1333-86-4	1.188	0.32		3180	
	plastics	epoxy resin	-	32.076	8.59		85860	
	inorganic material	silicondioxide	60676-86-0	204.334	54.69	63.60	546961	636001
leadfinish	non noble metal	tin	7440-31-5	4.118	1.10	1.10	11022	11022
plating	noble metal	silver	7440-22-4	1.663	0.45	0.45	4452	4452
glue	plastics	epoxy resin	-	0.675	0.18		1808	
	noble metal	silver	7440-22-4	2.026	0.54	0.72	5424	7232
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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